

# PATENT ABSTRACTS OF JAPAN

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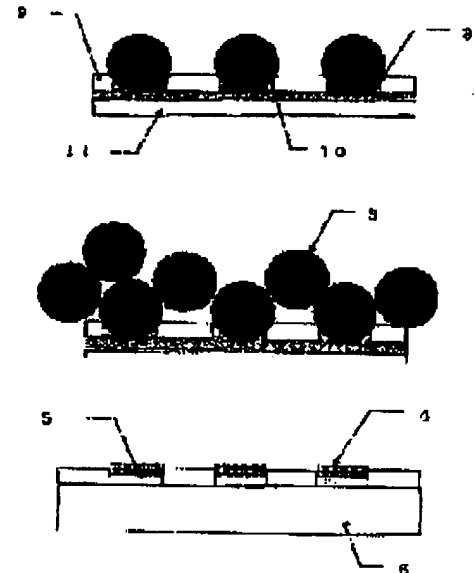
(21)Application number : 08-349927 (71)Applicant : SUMITOMO METAL MINING CO LTD  
(22)Date of filing : 27.12.1996 (72)Inventor : SHIMOJI TAKUMI

## (54) SOLDER BALL MOUNTING CARRIER FILM, ITS MANUFACTURE, AND SOLDER BALL-MOUNTING METHOD

### (57)Abstract:

**PROBLEM TO BE SOLVED:** To realize a solder ball mounting carrier film where flux is not required to be precisely controlled in-feed and a tool or the like is restrained from being contaminated with flux even if flux is excessively fed.

**SOLUTION:** A solder ball mounting operation is carried out by using a solder ball mounting carrier film composed of an adhesive tape which comprises a film 9 provided with through-holes 8, adhesive agent 10, and a base film 11 and solder balls. This solder ball mounting operation is carried out using the above solder ball mounting carrier film through such a manner that the outer pads 5 of a semiconductor package 6 are aligned with the solder balls 3 of the solder ball mounting carrier film and thermocompressed to fuse the solder balls 3. Then, the solder balls 3 are cooled below the melting point, whereby the solder balls 3 are fixed to the outer pads 5. Thereafter, the above carrier film is peeled off to transfer the solder balls 3 onto the outer pads 5.



### LEGAL STATUS

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